# DB27316

Silicon epitaxial planar type

For small current rectification DB2S316 in SSSMini2 type package

#### Features

- Short reverse recovery time t<sub>rr</sub>
- $\bullet$  Low forward voltage  $V_{\rm F}$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

#### Packaging

Embossed type (Thermo-compression sealing): 10000 pcs / reel (standard)

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Reverse voltage	V <sub>R</sub>	30	V	
Repetitive peak reverse voltage	V <sub>RRM</sub>	30	V	
Forward current (Average)	I <sub>F(AV)</sub>	100	mA	
Peak forward current	I <sub>FM</sub>	300	mA	
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	1	А	
Junction temperature	Tj	125	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	

Note) \*: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

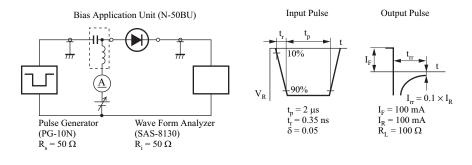
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	I <sub>R</sub>	$V_R = 30 V$			15	μΑ
Terminal capacitance	Ct	$V_{R} = 10 V, f = 1 MHz$		2		pF
Reverse recovery time *	t <sub>rr</sub>	$\begin{split} I_F = I_R = 100 \text{ mA}, \ I_{rr} = 0.1 \times I_R \ , \\ R_L = 100 \ \Omega \end{split}$		0.8		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 250 MHz

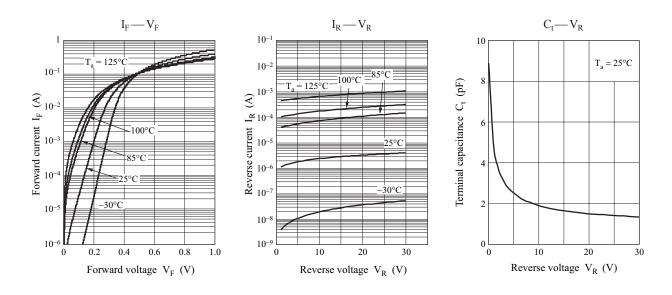
\*: trr measurement circuit



- Package
- Code
- SSSMini2-F4-B
- Pin Name
  - 1: Cathode
  - 2: Anode
- Marking Symbol: C7

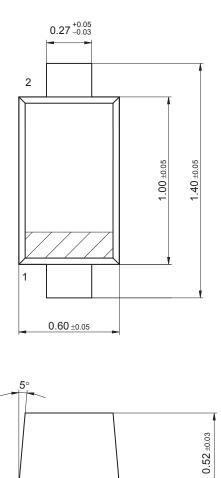
### DB27316

### **Panasonic**

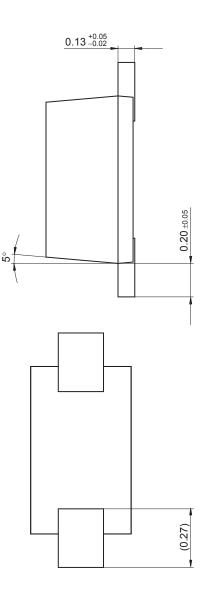


## SSSMini2-F4-B

Unit: mm



0 to 0.05



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